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(19) **KOREAN INTELLECTUAL PROPERTY OFFICE**

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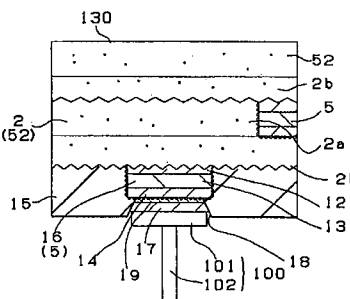
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**(54) CONDUCTIVE CONNECTING PIN AND PACKAGE BOARD**

**(57) Abstract:**

On the board provided with a conductive layer (5), a pad (16) is formed to fix a conductive connecting pin (100) on a package board (310). The conduction connecting pin (100) serves as electrical connection to a motherboard. The pad (16) is coated with an organic-resin insulating layer (15) having an opening section (18) from which the pad (16) is partially exposed. The conductive connecting pin (100) is fixed to the pad exposed from the opening section using a conductive adhesive (17), preventing the conductive connecting pin (100) from separating off the board at the time of mounting.



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